

L Number	Hits	Search Text	DB	Time stamp
1	1365605	organic polyimide polyimide photosensitive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 17:46
2	82594	(chip die semiconductor ic (integrated adj circuit)) same (organic polyimide polyimide photosensitive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 17:48
3	6381	((chip die semiconductor ic (integrated adj circuit)) same (organic polyimide polyimide photosensitive)) same (paddle pad diepad (die adj4 pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 17:49
4	51785	(chip die semiconductor ic (integrated adj circuit)) with (organic polyimide polyimide photosensitive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 17:49
5	3292	((chip die semiconductor ic (integrated adj circuit)) with (organic polyimide polyimide photosensitive)) same (paddle pad diepad (die adj4 pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 17:49
6	47872	(size smaller larger different) with (paddle pad diepad (die adj4 pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 17:50
7	990	((chip die semiconductor ic (integrated adj circuit)) with (organic polyimide polyimide photosensitive)) same (paddle pad diepad (die adj4 pad))) and ((size smaller larger different) with (paddle pad diepad (die adj4 pad)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 19:12
8	0	8-148518	JPO	2003/07/15 19:12
9	0	"148518"	JPO	2003/07/15 19:14
10	1	"08264706"	JPO	2003/07/15 19:13
11	0	"0848518"	JPO	2003/07/15 19:14
12	1	"08048518"	JPO	2003/07/15 19:15
13	1	"10242373"	JPO	2003/07/15 19:17
14	0	"110054685"	JPO	2003/07/15 19:18
15	1	"11054685"	JPO	2003/07/15 19:51
16	0	63-179554	JPO	2003/07/15 19:51
17	0	"179554"	JPO	2003/07/15 19:51
18	0	63-179554	JPO	2003/07/15 19:52
19	0	"630179554"	JPO	2003/07/15 19:52
20	1	"63179554"	JPO	2003/07/15 19:54
21	0	3-22465	JPO	2003/07/15 19:54
22	0	"1991022465"	JPO	2003/07/15 19:54
23	1	"03022465"	JPO	2003/07/15 19:55

L Number	Hits	Search Text	DB	Time stamp
1	1365605	organic polyimide polyimide photosensitive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 17:46
2	82594	(chip die semiconductor ic (integrated adj circuit)) same (organic polyimide polyimide photosensitive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 17:48
3	6381	((chip die semiconductor ic (integrated adj circuit)) same (organic polyimide polyimide photosensitive)) same (paddle pad diepad (die adj4 pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 17:49
4	51785	(chip die semiconductor ic (integrated adj circuit)) with (organic polyimide polyimide photosensitive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 17:49
5	3292	((chip die semiconductor ic (integrated adj circuit)) with (organic polyimide polyimide photosensitive)) same (paddle pad diepad (die adj4 pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 17:49
6	47872	(size smaller larger different) with (paddle pad diepad (die adj4 pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 17:50
7	990	((chip die semiconductor ic (integrated adj circuit)) with (organic polyimide polyimide photosensitive)) same (paddle pad diepad (die adj4 pad)) and ((size smaller larger different) with (paddle pad diepad (die adj4 pad)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 17:52